

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Mao-Lin KAO</td> <td>10/01/2012</td> </tr> <tr> <td>Hsu-Shui LIU</td> <td>10/01/2012</td> </tr> <tr> <td>Tien-Chen HU</td> <td>10/02/2012</td> </tr> <tr> <td>Li-Jen KO</td> <td>10/01/2012</td> </tr> <tr> <td>Hsiang-Yin SHEN</td> <td>10/01/2012</td> </tr> <tr> <td>Jiun-Rong PAI</td> <td>10/01/2012</td> </tr> </tbody> </table>		Name	Execution Date	Mao-Lin KAO	10/01/2012	Hsu-Shui LIU	10/01/2012	Tien-Chen HU	10/02/2012	Li-Jen KO	10/01/2012	Hsiang-Yin SHEN	10/01/2012	Jiun-Rong PAI	10/01/2012
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<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. VI</td> </tr> <tr> <td>Internal Address:</td> <td>Hsinchu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsinchu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-78</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	No. 8, Li-Hsin Rd. VI	Internal Address:	Hsinchu Science Park	City:	Hsinchu	State/Country:	TAIWAN	Postal Code:	300-78		
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PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13629498</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13629498										
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CORRESPONDENCE DATA															
Fax Number: <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 9498510633 Email: ltillman@mwe.com, mweipdocket@mwe.com Correspondent Name: John D. Magluyan Address Line 1: McDermott Will & Emery LLP Address Line 2: 4 Park Plaza, Suite 1700 Address Line 4: Irvine, CALIFORNIA 92614-2559															
ATTORNEY DOCKET NUMBER:	091393-0019														

CH \$40.00 13629498

NAME OF SUBMITTER:

John D. Magluyan, Reg. No. 56,867

Total Attachments: 2

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台積電編號: TSMC2012-0667; 本所編號: PECA 18628/5723

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned,

(1) Mao-Lin Kao, Hsu-Shui Liu, Tien-Chen Hu, Li-Jen Ko, Hsiang-Yin Shen, Jiun-Rong Pai

HEREBY SELL(S), ASSIGN(S) AND TRANSFER(S) TO

(2) Taiwan Semiconductor Manufacturing Company having a place of business at

(3) No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R. O. C.

(hereinafter called "ASSIGNEE") the entire right, title and interest in and to any and all improvements which are disclosed in the application for United States Letters Patent entitled

(4) SEMICONDUCTOR PROCESSING STATION AND METHOD FOR PROCESSING SEMICONDUCTOR WAFER

which application was:

(a) executed by the undersigned on (5a) The dates shown below

(b) filed on (5b) _____

And assigned Serial No. _____

including any and all United States letters Patents which may be granted on said application, and any and all extensions, divisions, reissues, substitutes, renewals or continuations of said application and patents, and the right to all benefits under all international conventions for the protection of industrial property and applications for said improvements.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee, its assigns or its successors in interest or its designee.

Upon said consideration, it is further agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining patent protection as provided herein.

DATE:

INVENTOR(S)

<u>2012/10/1</u>	<u>Mao-Lin Kao</u> Mao-Lin Kao
<u>2012/10/10</u>	<u>Hsu-Shui Liu</u> Hsu-Shui Liu
<u>2012/10/02</u>	<u>Tien-Chen Hu</u> Tien-Chen Hu
<u>2012/10/1</u>	<u>Li-Jen Ko</u> Li-Jen Ko
<u>2012/10/1</u>	<u>Hsiang-Yin Shen</u> Hsiang-Yin Shen
<u>2012/10/1</u>	<u>Jiun-Rong Pai</u> Jiun-Rong Pai

PATENT

REEL: 029339 FRAME: 0065

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WITNESSES:
